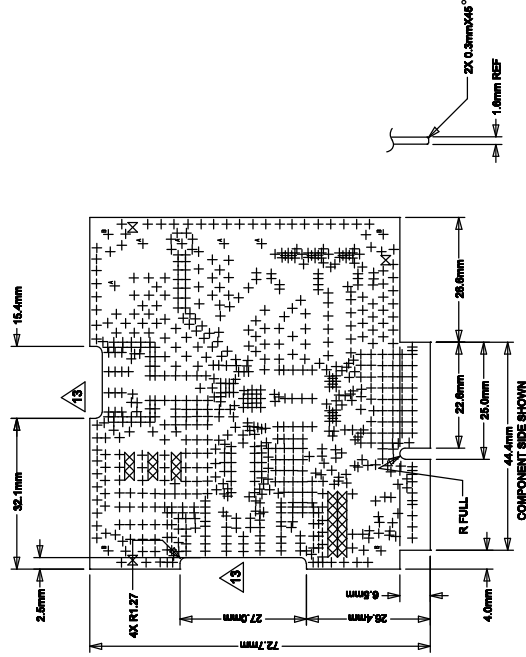


REVISION HISTORY				
ECO	REV	DESCRIPTION	DATE	APPROVED
	3	PROTO	06/21/08	

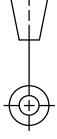


	SIZE	QTY	SYM	PLATED	TOL
	0.25	771	+	YES	+/-0.08
	0.89	23	⊗	YES	+/-0.08
	1.8	3	⊗	NO	+/-0.13
	2.4	5	+	YES	+/-0.13
	4.7	4	⊗	NO	+/-0.13

**UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ON ANGLES ±1°**

.XX ± 0.25
.XXX ± 0.127

THIRD ANGLE PROJECTION



DO NOT SCALE DRAWING

CONTRACT NO.

APPROVALS		DATE
DRAWN	MI	01/04/08
CHECKED		
APPROVED		
ENGINEER		

TITLE	DATE	TIME	LOCATION	STATUS
1. [REDACTED]	10/10/2023	14:30	Room 101	Completed
2. [REDACTED]	10/11/2023	10:00	Room 102	In Progress
3. [REDACTED]	10/12/2023	09:00	Room 103	Pending
4. [REDACTED]	10/13/2023	11:00	Room 104	Completed
5. [REDACTED]	10/14/2023	13:00	Room 105	In Progress
6. [REDACTED]	10/15/2023	15:00	Room 106	Pending
7. [REDACTED]	10/16/2023	16:00	Room 107	Completed
8. [REDACTED]	10/17/2023	17:00	Room 108	In Progress
9. [REDACTED]	10/18/2023	18:00	Room 109	Pending
10. [REDACTED]	10/19/2023	19:00	Room 110	Completed

**FAB, LTC2261CUJ, HIGH SPEED LOW POWER
125MSPS ADC FAMILY, CMOS**

SIZE B	CAGE CODE	DWG NO DC1370A	REV 3
SCALE 1/1	FILENAME:1370A-3.PCB		SHEET 1 OF 1

NOTES: UNLESS OTHERWISE SPECIFIED,

1. ARTWORK P/N DC1370A REV 3.
2. FAB PER IPC-A-600
3. PCB SHALL MEET RoHS COMPLIANCE
4. MATERIAL:

TRIAL:

- A. LAMINATE: EPOXY FIBERGLASS, NEMA GRADE FR-4
FLAMMABILITY RATING: 94 V-2 MINIMUM.**

5. FINISH:

- A. COATING: SOLDERMASK OVER BARE COPPER, COLOR, GREEN LPI.
B. PLATING: GOLD IMMERSION BOTH SIDES.
C. SILKSCREEN: COMPONENT SIDE WITH WHITE NON-CONDUCTIVE INK.
D. FINGER AREA: GOLD PLATE TO MIN. OF 0.0028mm PER MIL-G-4520A, TYP II, CL1, GRADE C, OVER 0.005mm LOW STRESS NICKEL PER QQ-N-280, CL2. SOLDER MASK TYPE: WET PHOTO-IMAGEABLE

6. TOLERANCES:

- A. WARPAGE: (0.075mm) MAX. ALONG THE LONGEST DIAG.
AS PER IPC-TM650 METHOD 2.4.22.
- B. ETCHING: +0.03mm, -0.3mm OF MASTER PATTERN.
- C. REGISTRATION: 0.075mm MAX.
- D. MASK THICKNESS: 0.025mm MIN., 0.076mm MAX.
- E. HOLE PLATING: 22um \pm 3um.

7. Size

8. HOLE DIAMETERS ARE POST-PLATED SIZES.
9. DEBURR AND BREAK AWAY SHARP EDGES.
10. DO NOT ALTER THICKNESS: e.g. TO ADD LOGO OR DATE CODE
11. OUTER DIELECTRIC TISSUE: TARGET 0.0-0.1MM USING
1.143mm THICKNESS. SEE STAMPING DIAGRAM.
12. 4.00mm THICKNESS. TO BE KEPT CONSTANT OF
4.00mm. SUBJECT TO CHANGE BY MANUFACTURER,
DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS.
13. INNER AND OUTER LAYER COPPER SHALL BE EXPOSED
ALONG BOARD EDGES. DO NOT MODIFY INNER LAYER
COPPER BACKGROFF OUTLINE.